

Title (en)

ARRANGEMENT IN A MULTILAYER FLOOR COVERING

Title (de)

ANORDNUNG VON HALBLEITERCHIPS IN EINEM MEHRLAGIGEN BODENBELAG

Title (fr)

ARRANGEMENT DANS UN REVÊTEMENT DE SOL MULTICOUCHE

Publication

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Application

EP 08774821 A 20080707

Priority

- EP 2008058747 W 20080707
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Abstract (en)

[origin: WO2009007335A2] The invention relates to an arrangement of chips (10) bonded with sensors (7) in a multilayer floor covering. In order further to improve an arrangement of the type under consideration herein, in a simpler way of technical production, the invention proposes that in a first upper layer (1) circuit paths (4) are formed, separated from each other in a plane, to provide power to a chip (10), that a second middle layer (2) is provided in which the chip (10) is located, and that a third lower layer (3) is provided which likewise is connected electrically to the chip (10), wherein sensors (7) are located in the surface gaps between the chips (10).

IPC 8 full level

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